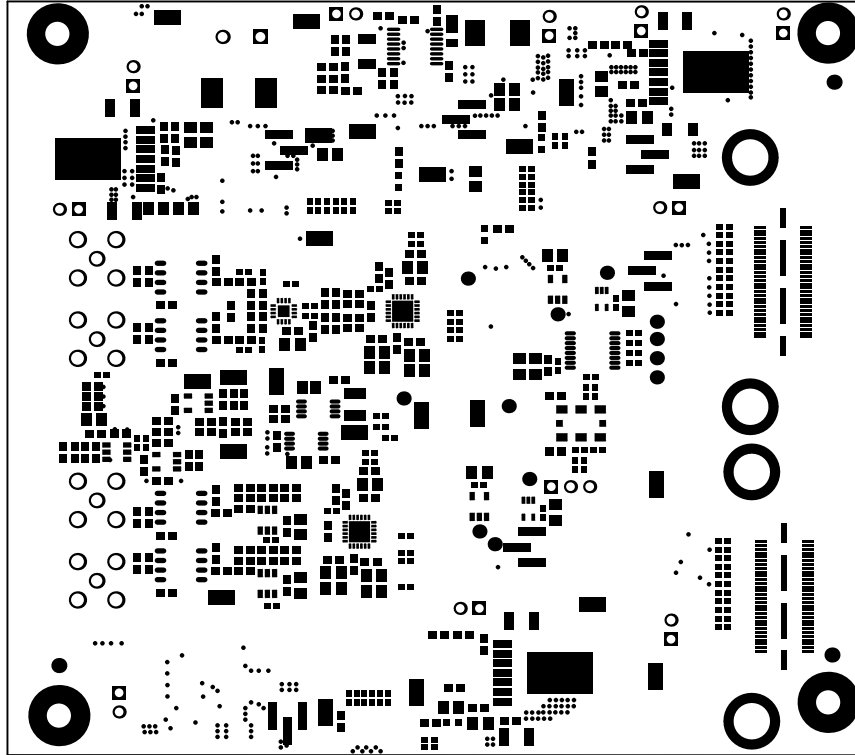
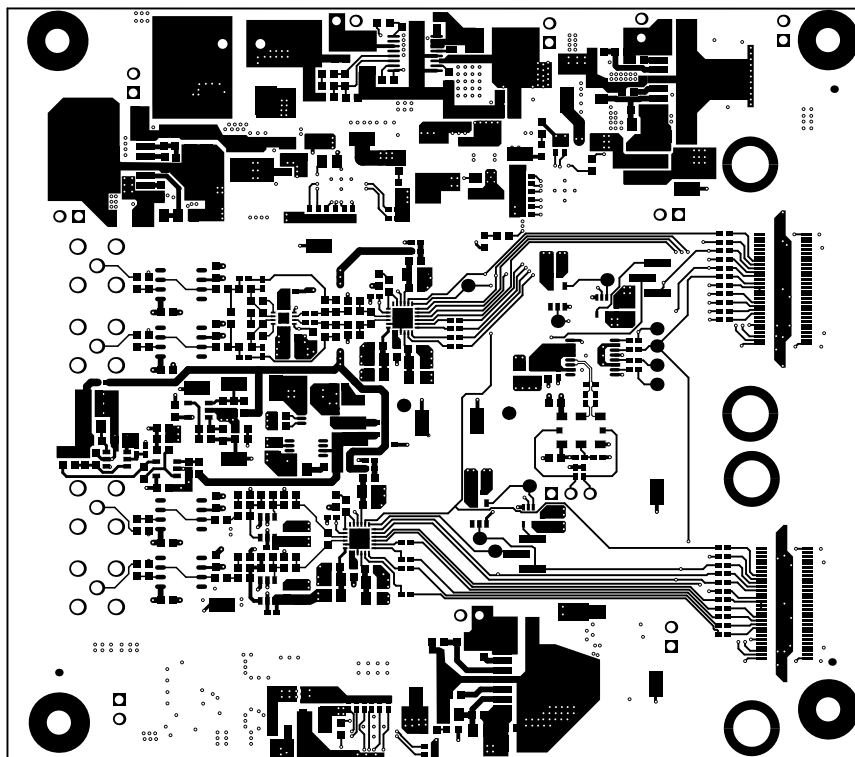


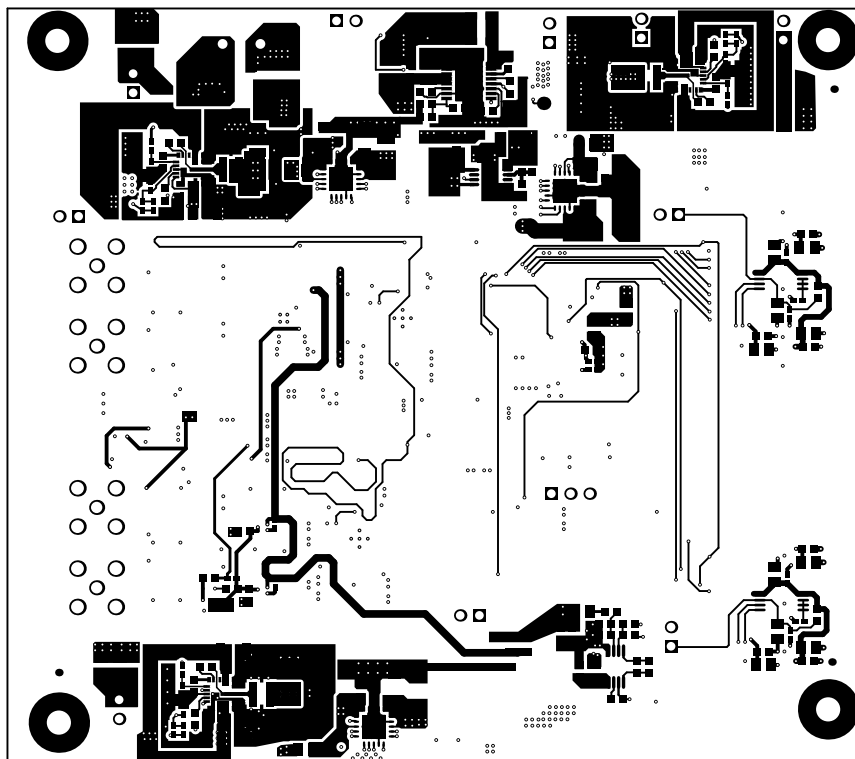
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01056		
PLOT NAME = Top Overlay	GENERATED : 2017/11/09 11:19:27	TEXAS INSTRUMENTS	



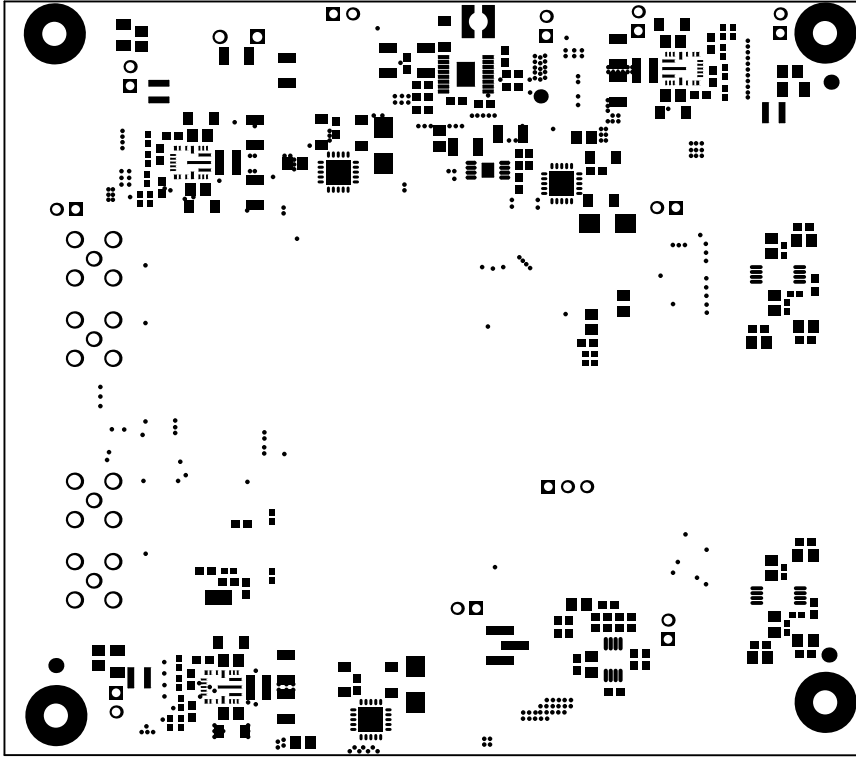
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01056		
PLOT NAME = Top Solder Mask	GENERATED : 2017/11/09 11:19:28	TEXAS INSTRUMENTS	



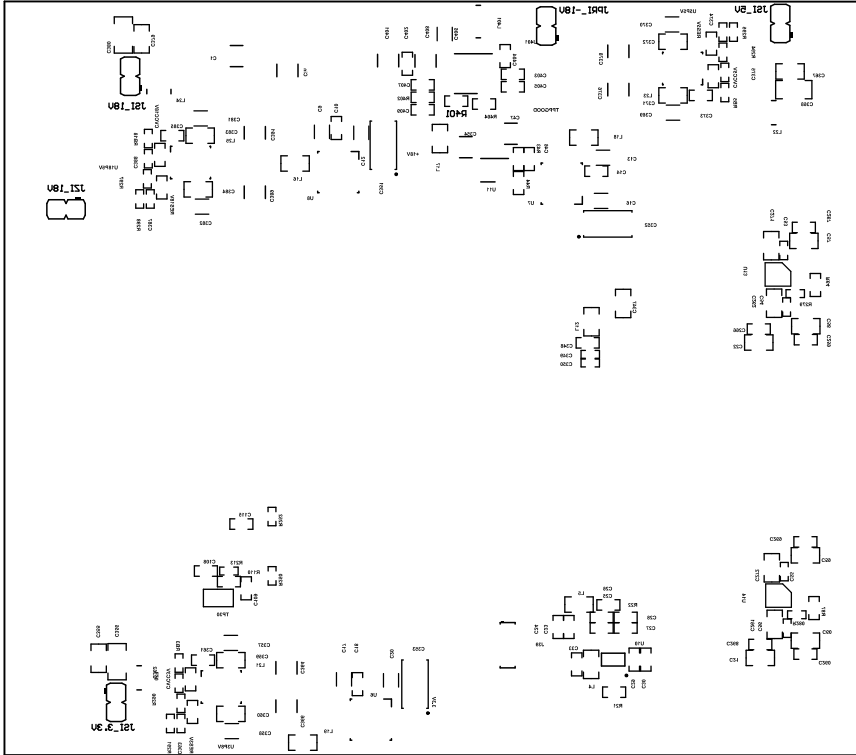
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: 01056		
PLOT NAME = Top Layer	GENERATED : 2017/11/09 11:19:29		TEXAS INSTRUMENTS



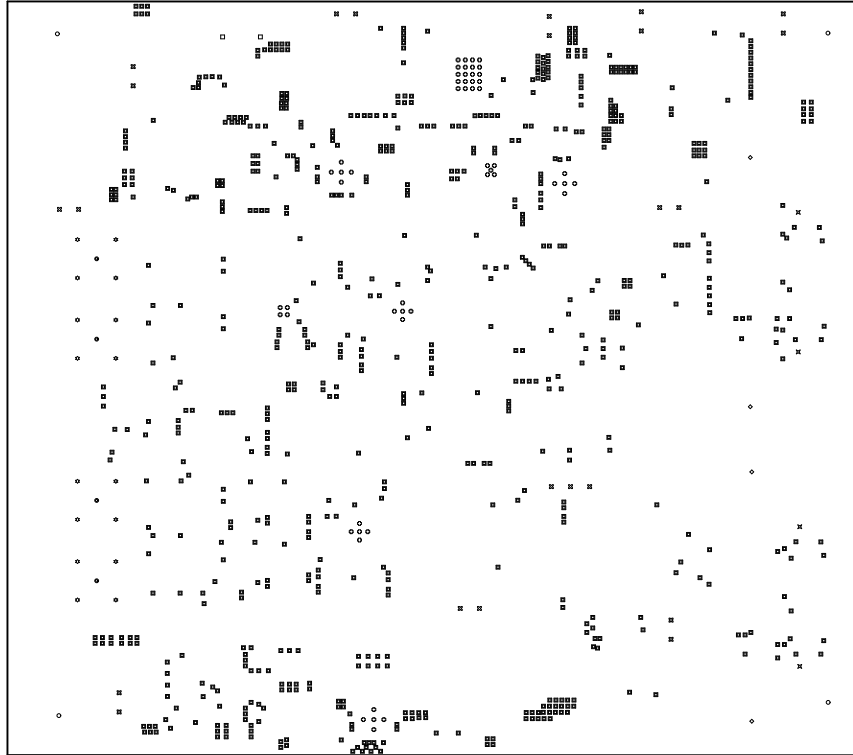
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: 01056		
PLOT NAME = Bottom Layer	GENERATED : 2017/11/09 11:19:30		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01056		
PLOT NAME = Bottom Solder Mask	GENERATED : 2017/11/09 11:19:31		TEXAS INSTRUMENTS

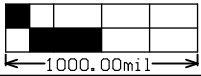
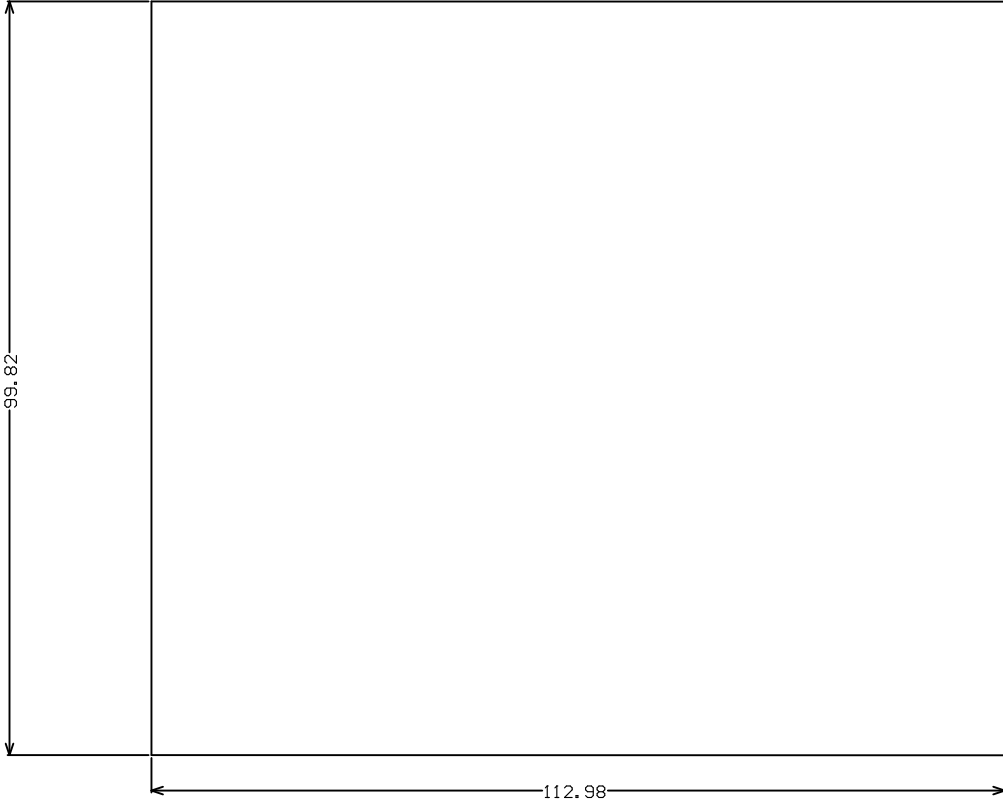


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01056		
PLOT NAME = Bottom Overlay	GENERATED : 2017/11/09 11:19:32	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	4	40.00mil (1.016mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
◇	4	173.23mil (4.400mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊗	54	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
■	716	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊗	23	45.28mil (1.150mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
□	2	51.18mil (1.300mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
●	4	59.06mil (1.500mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊗	16	66.93mil (1.700mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
827 Total						

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01056		
PLOT NAME = Drill Drawing	GENERATED : 2017/11/09 11:19:34		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01056	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01056		
PLOT NAME = Board Dimensions	GENERATED : 2017/11/09 11:19:36		TEXAS INSTRUMENTS

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